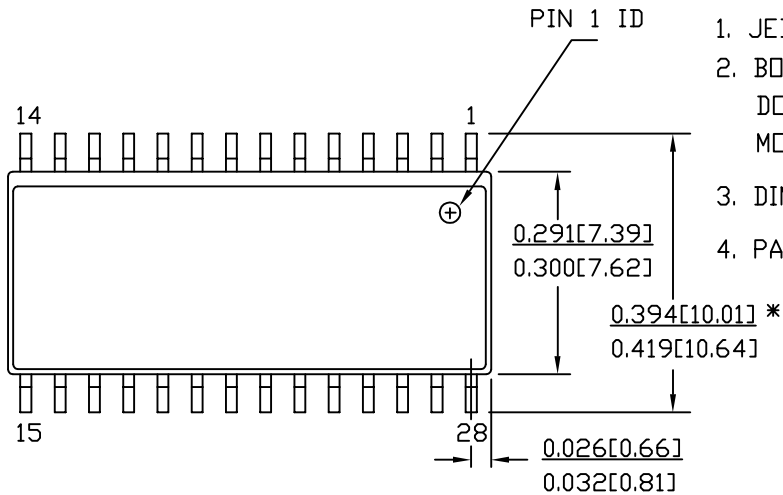


28 Lead (300 Mil) SOIC - S21

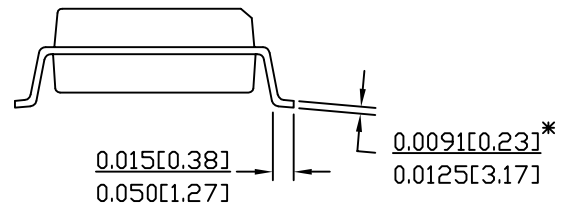
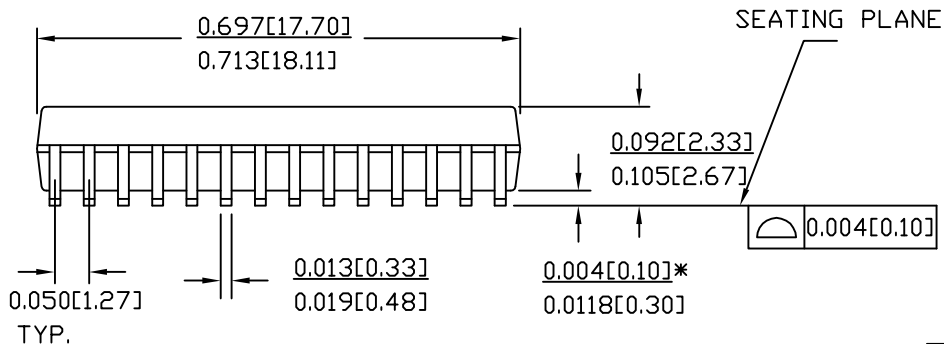
REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	N/A	N/A	N/A	N/A
1	-	*A	49383	CHG. TITLE / CHG. DIM.S AT *	04/08/97	N/A
1	-	*B	125491	ADD [MM] DIM.	03/18/03	N/A
1	-	*C	128909	ADD JEDEC #/ ADD PKG. WEIGHT/ ADD SZ PART #.	08/05/03	N/A
1	-	*D	413084	ADD NOTES - JEDEC REFERENCE MO-119	12/10/05	ONG
1	-	*E	2868899	- MOLD PROTRUSION/END FLASH INFORMATION CHANGED TEMPLATE CHANGE TITLE FROM 28LD (300 MIL) SOIC PKG OUTLINE TO PACKAGE OUTLINE, 28L SOIC .713X.300X.0932 INCHES	01/28/10	QAD
1	-	*F	3146096	ECN SUNSET NO CHANGE	01/18/11	QAD

NOTE :

1. JEDEC STD REF MO-119
2. BODY LENGTH DIMENSION DOES NOT INCLUDE MOLD PROTRUSION/END FLASH,BUT DOES INCLUDE MOLD MISMATCH AND ARE MEASURED AT THE MOLD PARTING LINE. MOLD PROTRUSION/END FLASH SHALL NOT EXCEED 0.010 in (0.254 mm) PER SIDE
3. DIMENSIONS IN INCHES MIN.
MAX.
4. PACKAGE WEIGHT 0.85gms



PART #	
S28.3	STANDARD PKG.
SZ28.3	LEAD FREE PKG.



UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ARE:		DESIGNED BY N/A	DATE N/A	
DECIMALS .XX ± 0.05 .XXX ± .XXXX ±	ANGLES ± 1°	DRAWN BY ONG	DATE 12/10/05	
		CHECKED BY TSV	DATE 01/28/10	TITLE PACKAGE OUTLINE, 28L SOIC .713X.300X.0932 INCHES
		APPROVED BY QAD	DATE 01/28/10	SIZE A
		APPROVED BY JGUA	DATE 01/28/10	PART NO. SEE NOTE
		APPROVED BY N/A	DATE N/A	DWG NO 51-85026
				REV *F
				SCALED TO FIT N/A
				SHEET 1 of 1

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